

12 November 2010

William reported that the TID prototypes are ready for testing with the SD and CTP. The I²C functions will be exercised and the CTP can be used to verify the TID→Switch card interface.

The definitions for the 32 trigger signals have been determined and to save I/O space on the TS we will send the GTP outputs to the TS from a rear transition module. The connectors will be four 4X infiniband style. These signals are not serial links, but the connectors and cable support the high speed LVPECL signaling that will be used between the GTP and TS.

The TS specification has been updated and circulated for comments. The design of the board is not the highest priority this year because the TID will need to be completely tested with multiple modules in a crate to measure and record performance of the trigger link, clock distribution and zero latency setup.

Six V1290 TDC fan-out boards have been sent for assembly. The initial partially assembled board has been tested and final test results will be reported.

1. FIRMWARE TESTING

17-December 2010

→The 2eSST firmware revision that Ed has created has been used in the SSP and TI-D. Ed reports that he will test the revision also with the FADC250-v2 boards.

→There is a large amount of firmware development activities for each board, so it is not productive to list these here, but suffice it to say, that these development activities have been successful and final firmware revisions will be ready by the time these boards are in production. (end of FY11)

12 November 2010

Firmware updates will continue for the prototype board revisions. Once all tests have been completed for all features of the boards, (SD; TID, for example) the final software libraries can be released.

29 October 2010

No specific firmware topic was discussed but firmware development and iterations are a never ending activity. I know Nick will be modifying and testing SD firmware for the Rev-1 boards, and there are several functions that will need to be completely re-written. SSP firmware testing continues also and specific details are included in Ben's directory.

22 October 2010

Not exactly a firmware discussion point here, but no further discussion about using a common VME 'Broadcast' addressing scheme to manage common module commands has taken place. I believe this would be a valuable time saving method for common commands, and can be handled in the FPGA.

We have determined that there will be a single GTP in switch slot A of the global trigger crate, so the backplane mapping can remain the same as a front-end crate. The SSP will have to be modified, but the pair mapping is a minor revision. This will restore the token passing to the SSP and eliminate the signal fan-out requirement for the GTP.

2. SUB-SYSTEM PROCESSOR (SSP)

17-December 2010

→The SSP prototype is virtually complete with SODIMM memory testing and P0 gigabit lane testing still to be fully verified. The SSP BGA issues have been resolved and the design will be virtually unchanged for the production version.

→The SSP has been proposed as a data readout/trigger interface for up to 32 detector readout devices. The proposed idea may be a perfect solution for the Hall B central detector readout scheme and the fiber links from up to 32 custom readout devices can be connected to a single

SSP. The SSP engine would manage the data reduction and local trigger algorithms for up to 32 detector readout devices, and as a payload module, the detector data will be read out through VME2eSST. Nice development and further details will emerge soon.

12 November 2010

Ben reports that other high priority work has pushed the SSP testing and firmware iteration activities back. The SSP has been tested and there will be minor ECO to the prototype. There are several tests (SODIMM for example) that will need to be completed, but the SSP is ahead of schedule and will be used for the two crate test that is planned later this year.

29 October 2010

Ben reports that the SSP testing will continue and that the board was repaired (re-balled/reflowed) so that the intermittent pins are now working. The SSP complete verification will need to take a higher priority to fully qualify the SSP design. At some point soon, this module design and VME register map will need a CODA 'driver', but there are still many tests to perform.

22 October 2010

Ben reports that the SSP has been repaired and has been sent back to Jlab. He will continue testing the SSP and can continue to fully check all functions. (SODIMM – DDR2, etc). The module will need to be tested with the TI-D, and of course the SD board to verify the initial global trigger crate 'system'. We can also use the existing CTP in another crate to record and test data transfer from two CTP to a single SSP.

1 October 2010

Ben has tested virtually all functions of the SSP with the exception of the SDRAM and output serial streams to the GTP. The board has been sent to the assembler for reflow/repair of one of the FPGA that appears to have solder connectivity problems. Fiber transceivers have been exercised and BitErrorRate(BER) testing has been measured to be well within limits.

3. CUSTOMERS

17-December 2011

→There may be a need from the Medical Imaging group to use a single FADC250 module for verification of new front end electronics designs. The use of a single board will be an interim solution until the new custom readout design is complete.

12 November 2011

The injector polarimeter folks presented results from a FADC250 board and will continue to develop their applications. Another FADC250 was given to them. I will not be long before all the original prototype boards will be replaced, but those prototypes certainly produced a great deal of development success.

29 October 2010

No new reports and no new customers lately.

4 "B" Switch - Signal Distribution Module (SD)

17-December 2011

→Progress continues and the two rev-1 SD boards have been updated with the latest ECO for the power supply section. Nick has set up the original SD and TI to establish the I²C communication link, and has loaded the I²C firmware on the new SD board. The new TI-D module uses a different I²C address scheme which does not work with the original I²C firmware. This will have to be resolved when William and Nick return from the holiday break.

→Hall B purchased components for eight(8) SD boards, so as soon as ALL ECO have been identified and crate testing is complete, the final revision of the SD will be ready to order.

→Nick has updated the SD documentation and the new front panel design is complete and looks nice. Significant testing remains for the thorough analysis of the PLL clock jitter attenuation function including all other SD functions using a full crate of FADC250 are on the horizon.

12 November 2011

The two rev-1 SD boards are being tested and minor ECO will be required. Nick will continue testing all sections and has started the firmware revisions. The new firmware will need to be tested soon with the revised TID and performance results for clock jitter distribution etc will be recorded.

Scott has completed two switch card test boards that will be used during testing of the FADC250 plus the SD card. These cards provide loopback signaling, clock distribution, and test points for the SD and FADC250 modules. The boards will be received and assembled soon.

29 October 2010

The parts and boards have been sent to the assembler, and we have paid for a 7 day delivery. The front panel and partial assembly will be completed as soon as we receive the two modules, then Nick can begin the testing.

This is a good place to list the two Switch card boards that Scott has designed and these are his 1st Altium designs. The two boards have different functions but will provide the functions of loop back to emulate the CTP and the board will also provide a clock signal to drive a FADC250 during single board testing.

The second board is a B_Switch card that also provides loopback for testing specific signals and distributes signals to the proper payload slots.

These two boards are low cost and will be sent for manufacturing before mid-November.

5. System Diagrams & Test Stand Activities

17-December 2010

→Mark and Chris have revived the CD3 drawings for the trigger fiber optic infrastructure drawings. Ben and Chris met with a supplier of the fiber and patch panels and we will request a price estimate for the fiber trunk cables included the patch panels and patch cables. The drawings will be updated to reflect the cable lengths as shown in the Hall D 3D CAD model. (Tim and Chuck) This work will have to be completed for Hall B at some point before FY12.

12-November 2010

Preliminary trigger system drawings were produced for CD3 reviews, and the number and style of fiber optic cabling was included. A price estimate will be requested from at least one source soon, to verify that the cost will be within the scope of the planned budget.

16 July 2010 (Keep this because it needs to be implemented and tested at some point)

So this is a good place for the discussion about pedestal subtraction and trigger signals that occur close together. These topics were raised at the recent trigger workshop and it was suggested that we dedicate some time to these topics.

- A) How are pedestals handled in the trigger summation scheme, and how are they handled during data extraction? (We will certainly need to develop a consistent scheme for determining pedestals and subtracting them from the raw samples).
- B) When multiple triggers fire (in short succession), what is the implication for duplicate data recorded in the event stream?

Discussion points for each topic below:

- A) Some form of pedestal subtraction has always been part of the firmware plan for each channel and for the summing of the signals. Ben presented a few methods for this pedestal subtraction at the workshop, and the pedestal subtraction has not been implemented on the flash board firmware. We did not implement pedestal subtraction

for any of the tests using the two crates last year, so optimization of this method will need some work.

The pulse window charge value (sum of points for a given pulse) will need to have a pedestal correction. This pedestal correction will be stored in a register for each channel and the method for collecting the pedestal value will need to be determined.

Gerard uses some method (or is planning a firmware method?) so it would be a good idea to request his VHDL code and Hai can verify if it can be re-used for the FADC250.

- B) Multiple triggers will occur for a given trigger 'window'. The implication of duplicate data seems to be a concern, and for triggers that are close together, some detector signals (data) will appear in both triggers. The GTP can record the number of times the global trigger equation has produced a valid trigger within the global trigger 'window'. The GTP window allows the alignment of the subsystem detectors and will be able to determine if the global trigger equation has been validated. Multiple validations are possible within the GTP 'window' and these valid trigger pulses will be sent to the TS. The TS will receive this information and will also control the separation of triggers that are driven to the front end crates. The number of valid triggers within the global trigger window can be stored as a trigger type or scaled. There is a minimum trigger signal separation requirement at the FADC250 which is approximately 70ns.

Crate Trigger Processor (CTP)

17-December 2010

→The old I²C firmware in the CTP is not compatible with the new I²C revision that was implemented by William in the new TI-D. Brian has a CTP and new TI-D but will need to have William modify his I²C firmware so that he can complete the work needed for the CTP software library.

→The heat sink material has been machined and the front panels also. The machined panels and heat sinks will be ready for assembly by the new year.

→One of the CTP has been assembled with a high speed grade V5FX70T FPGA and will be used to fully qualify the v2 FADC250 at 5Gbps/lane.

→Scott will work with one of the original CTP to become familiar with the design, Chipscope, and other features of the board. Scott can then begin testing the new CTP assemblies in January.

→Scott has completed the design for two switch card test boards and these have been assembled and are in use by Hai and Nick for testing their boards. The documentation for these switch card test boards has been completed by Scott.

12-November 2010

Two more CTP have been received and the heat sinks, front panel are almost ready for assembly. These modules will need to be tested and prepared for additional testing (5Gbps) with the version 2 FADC250 boards.

Bryan has one of the initial prototypes CTP and will continue testing the software library with the latest TID firmware.

29 October 2010

No news is good news and two CTP will be shipped to JLAB on 11-Nov. These CTP will need to be verified before testing in conjunction with the new FADC250-V2 boards, and at least one of the boards will be tested at the 5Gbps rate along with the FADC250-V2 board that has the higher speed 'FX70T part

22 October 2010

Two CTP are at the assembler and are due to be completed by 11-Nov. Testing the CTP can begin as soon as they are received. Recall that at least one of the CTP will have the faster

grade parts and will be tested at 5Gbps in conjunction with the FADC250-V2 modules. Plenty of test activities will begin once we receive these boards.

6. Projects for FY11 (GTP and Global Crate Developments)

17-December 2010

→We dedicated a significant portion of the 10-Dec meeting to discussion of the trigger board and system schedule for the remainder of FY11 and test integration activities planned for FY12 including what I call “Pre-commissioning” activities that will need significant resources once the crates and modules are installed in the hall(s).

→The preliminary schedule was distributed and the engineers for each board development project provided feedback and adjustments were made to show the activities needed to achieve a reasonable estimate-to-completion for almost all the trigger system board designs. It is realistic to expect that the final board designs will be ready for production orders as soon as FY12 begins and possibly sooner. Budget allocations for the volume purchases of SD and TI-D for instance, may need to be moved to FY12, but the goal is to have the board design files ready for order by end of FY11.

→Alex and Chris have created schedules that show activities from the Hall D P6 schedules and there are several activities that will need to be assigned new IDs.

12-November 2010

→Large portion of the meeting was to discuss the ‘integration’ testing required for all of the latest revisions of the front end trigger modules. Virtually all the boards are at the first revision stage and will need to be tested with in a full crate. The FADC250 pre-production schedule is progressing well, so the SD & TID will need to be fully tested by the time we have more than 16 FADC250.

→Goals of the integration testing:

- Verify clock distribution through TID-SD and measure jitter to front end boards
- Verify trigger rate and readout rate for a variety of occupancy levels.
- Verify token passing scheme
- Verify CTP operation with sixteen FADC250 @2.5Gbps
- Test playback mode feature on two crates and verify operation with SSP.
- Measure and record trigger latency. (Could include SSP)
- I am sure there are more milestone tests, but we can iterate the list.

I have an integration test schedule developed and we can discuss the dateline at the meeting.

29 October 2010

More discussions about the TS and several people sent comments to William regarding the 1st draft of the specification. The front panel I/O has been discussed and will be defined soon, and of course the definitions will be implemented on the GTP. Chris needs to update the global trigger pair map, and show a SD in the switch B slot.

22 October 2010

We have had several good discussions about the GTP and have reviewed requirements for Hall D and a proposal by Hall B to support more than one GTP. Present design plans include support of up to 8 SSP by a single GTP. So, 64 front end Level 1 crates can be supported, which easily satisfies Hall D for instance. More SSP can be supported but the additional payload port slots must be wired on the GTP. We will definitely support an Ethernet connection to the GTP and it is not clear if we implement an Ethernet pair from PP17 considering the CPU candidates may not have the P0 interface.

The GTP prototype will be a very close cousin to the CTP and will not have to support the fan-out features of the SD board (Switch-B). The pair mapping sketch for the global trigger

crate will be updated to show the details and will effectively be a replica of the front end crate map.

Scott has learned the Altium tools and will begin with test board designs that will be used to test the new version of the FADC250 and to support testing of the CTP and SD boards. These boards are straightforward designs and offer very good practical experience. Soon after the schematics for the GTP prototype will be committed.

1 October 2010

GTP progress pace will improve significantly and Scott has started some research for implementing more than eight(8) SSP in the global trigger crate using cross point switches. We have to clearly understand the signal mapping already established for the TID and SSP, and also clearly take into consideration the duplicate function of the GTP in the B-Switch slot as the Signal Distribution functions cannot be omitted.

ACTION ITEMS: Next meeting → Friday 7 January 2011!! 10AM in F226